

## ABSTRACT

At a lateral position of a mold cavity counterpart (3) of a non-leaded leadframe (2), a notch (6) used for injecting resin is provided. Molten resin is injected into a  
5 mold cavity (34) through the resin injection notch (6) from a resin path (35, 36) provided at the lateral position of the mold cavity (34). Thus, the space between mold cavity counterparts (3) of the non-leaded leadframe (2) arranged in a matrix form can be decreased. Therefore, the number of packages molded using one non-leaded leadframe (2) can be increased. As a result, the productivity of packages enclosing electronic  
10 components (4) is improved.